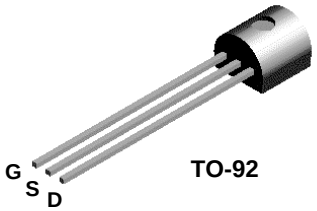
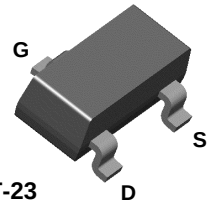
FAIRCHILD
SEMICONDUCTOR TM

2N5484 MMBF5484
2N5485 MMBF5485
2N5486 MMBF5486



TO-92



SOT-23
Mark: 6B / 6M / 6H

NOTE: Source & Drain are interchangeable

N-Channel RF Amplifier

This device is designed primarily for electronic switching applications such as low On Resistance analog switching. Sourced from Process 50.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{DG}	Drain-Gate Voltage	25	V
V_{GS}	Gate-Source Voltage	- 25	V
I_{GF}	Forward Gate Current	10	mA
T_J , T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:
1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		2N5484-5486	*MMBF5484-5486	
P_D	Total Device Dissipation Derate above 25°C	350 2.8	225 1.8	mW mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	556	°C/W

*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

©1997 Fairchild Semiconductor Corporation

N-Channel RF Amplifier
(continued)

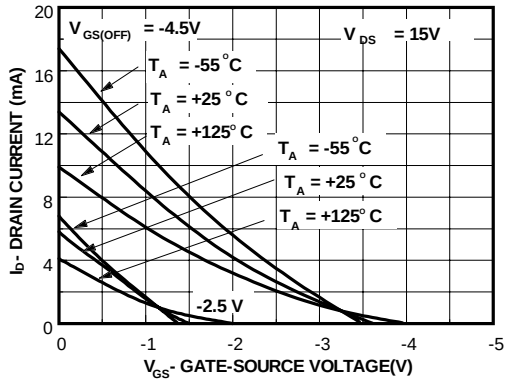
Electrical Characteristics
TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
$V_{(BR)GSS}$	Gate-Source Breakdown Voltage	I_G = - 1.0 µA, V_{DS} = 0	- 25			V
I_{GSS}	Gate Reverse Current	V_{GS} = - 20 V, V_{DS} = 0			- 1.0	nA
		V_{GS}= - 20 V, V_{DS}= 0, T_A= 100°C			- 0.2	µA
$V_{GS(off)}$	Gate-Source Cutoff Voltage	V_{DS} = 15 V, I_D = 10 nA **5484**	- 0.3		- 3.0	V
		5485	- 0.5		- 4.0	V
		5486	- 2.0		- 6.0	V
ON CHARACTERISTICS						
I_{DSS}	Zero-Gate Voltage Drain Current*	V_{DS} = 15 V, V_{GS} = 0 **5484**	1.0		5.0	mA
		5485	4.0		10	mA
		5486	8.0		20	mA
SMALL SIGNAL CHARACTERISTICS						
g_{fs}	Forward Transfer Conductance	V_{DS} = 15 V, V_{GS} = 0, f = 1.0 kHz				
		5484	3000		6000	µmhos
		5485	3500		7000	µmhos
		5486	4000		8000	µmhos
$Re(y_{is})$	Input Conductance	V_{DS} = 15 V, V_{GS} = 0, f = 100 MHz				
		5484			100	µmhos
		V_{DS} = 15 V, V_{GS} = 0, f = 400 MHz				
		5485 / 5486			1000	µmhos
g_{os}	Output Conductance	V_{DS} = 15 V, V_{GS} = 0, f = 1.0 kHz				
		5484			50	µmhos
		5485			60	µmhos
		5486			75	µmhos
$Re(y_{os})$	Output Conductance	V_{DS} = 15 V, V_{GS} = 0, f = 100 MHz				
		5484			75	µmhos
		V_{DS} = 15 V, V_{GS} = 0, f = 400 MHz				
		5485 / 5486			100	µmhos
$Re(y_{fs})$	Forward Transconductance	V_{DS} = 15 V, V_{GS} = 0, f = 100 MHz				
		5484	2500			µmhos
		V_{DS} = 15 V, V_{GS} = 0, f = 400 MHz				
		5485	3000			µmhos
		5486	3500			µmhos
C_{iss}	Input Capacitance	V_{DS} = 15 V, V_{GS} = 0, f = 1.0 MHz			5.0	pF
C_{rss}	Reverse Transfer Capacitance	V_{DS} = 15 V, V_{GS} = 0, f = 1.0 MHz			1.0	pF
C_{oss}	Output Capacitance	V_{DS} = 15 V, V_{GS} = 0, f = 1.0 MHz			2.0	pF
NF	Noise Figure	V_{DS}= 15 V, R_G = 1.0 kΩ,				
		f = 100 MHz **5484**			3.0	dB
		V_{DS}= 15 V, R_G = 1.0 kΩ,				
		f = 400 MHz **5484**		4.0		dB
		V_{DS}= 15 V , R_G = 1.0 kΩ,				
		f = 100 MHz **5485 / 5486**			2.0	dB
		V_{DS}= 15 V, R_G = 1.0 kΩ,				
		f = 400 MHz **5485 / 5486**			4.0	dB

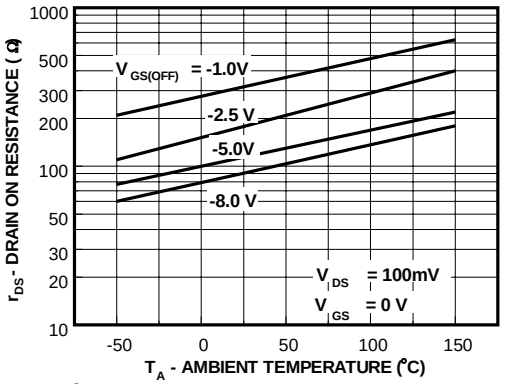
*Pulse Test: Pulse Width ≤ 300 ms, Duty Cycle ≤ 2%

Typical Characteristics

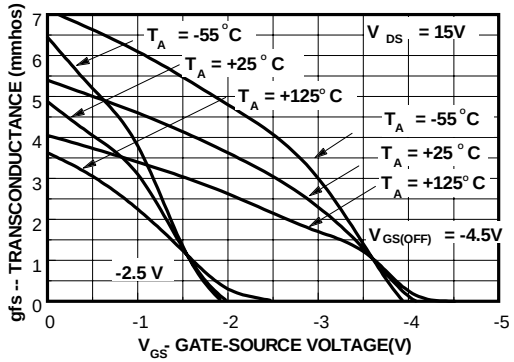
Transfer Characteristics



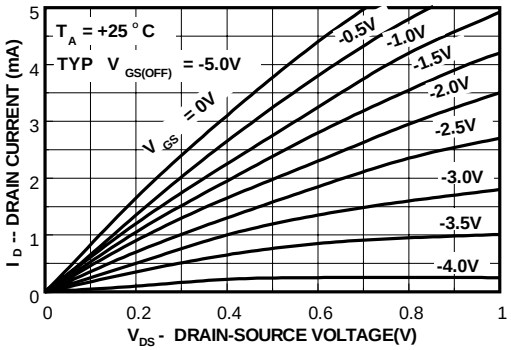
Channel Resistance vs Temperature



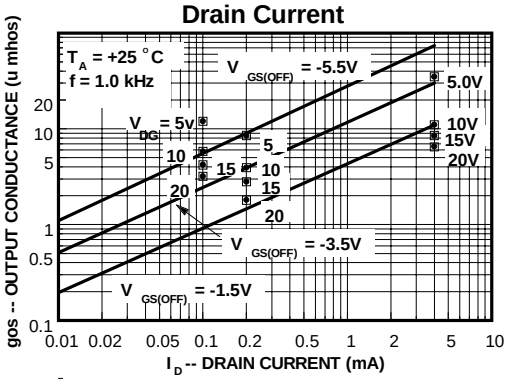
Transconductance Characteristics



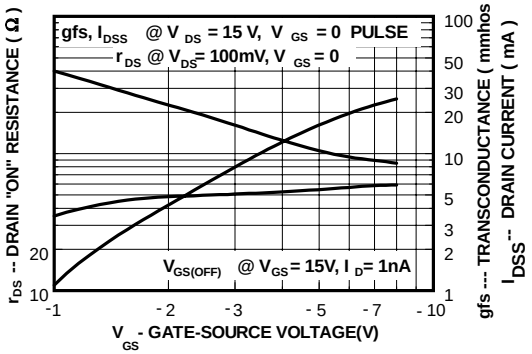
Common Drain-Source Characteristics



Output Conductance vs Drain Current

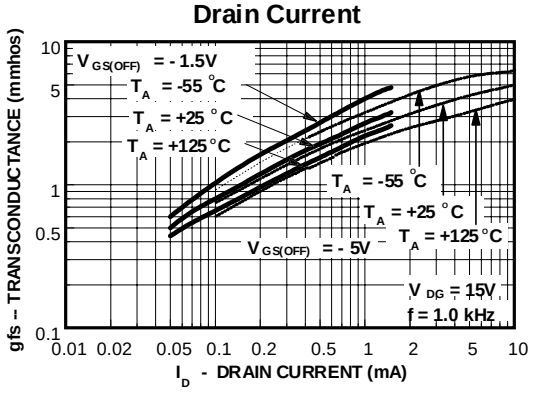


Transconductance Parameter Interactions

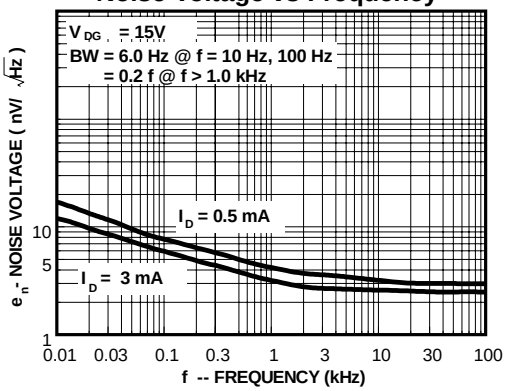


Typical Characteristics (continued)

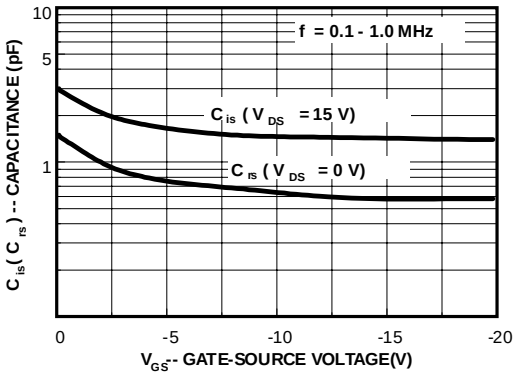
Transconductance vs Drain Current



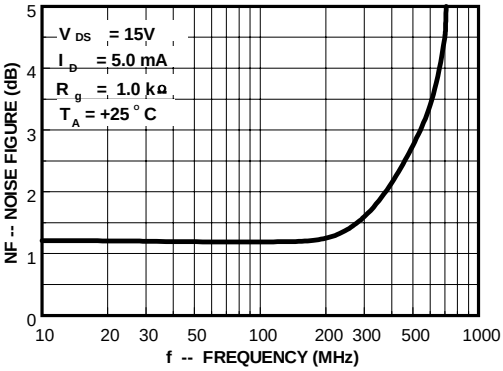
Noise Voltage vs Frequency



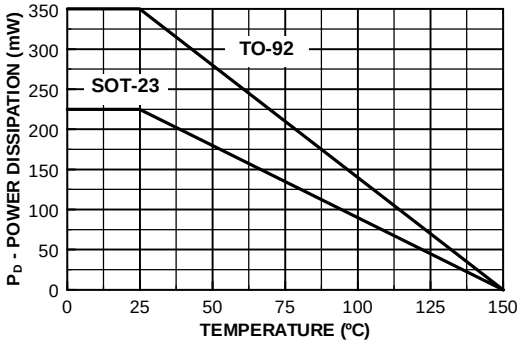
Capacitance vs Voltage



Noise Figure Frequency

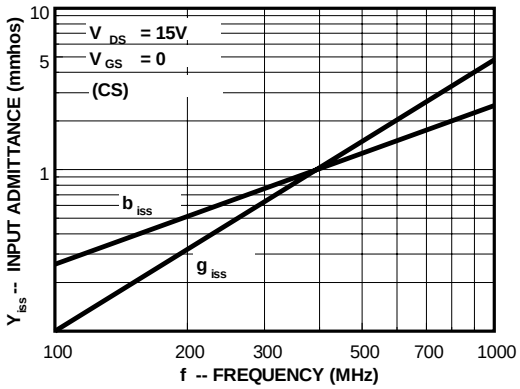


Power Dissipation vs. Ambient Temperature

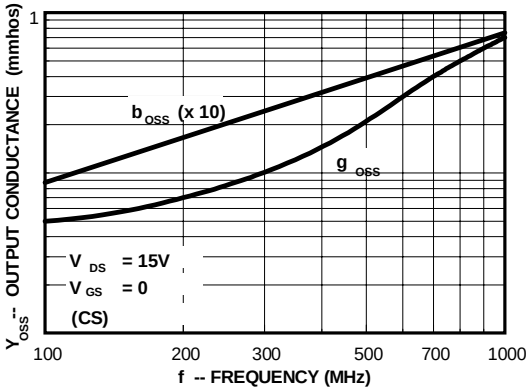


Common Source Characteristics

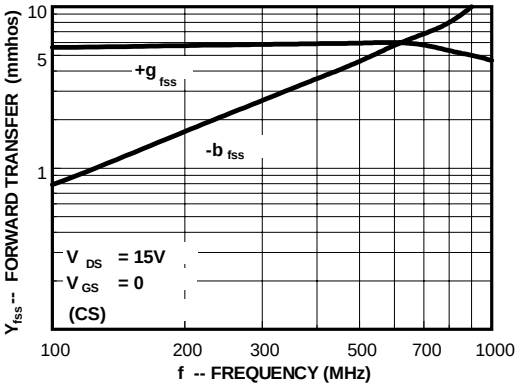
Input Admittance



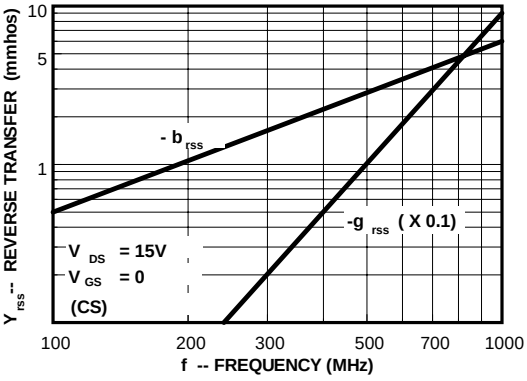
Output Admittance



Forward Transadmittance

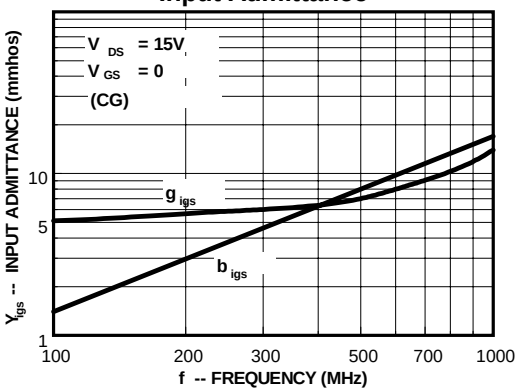


Reverse Transadmittance

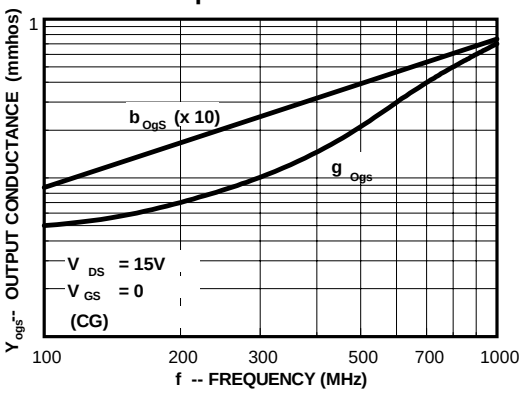


Common Gate Characteristics

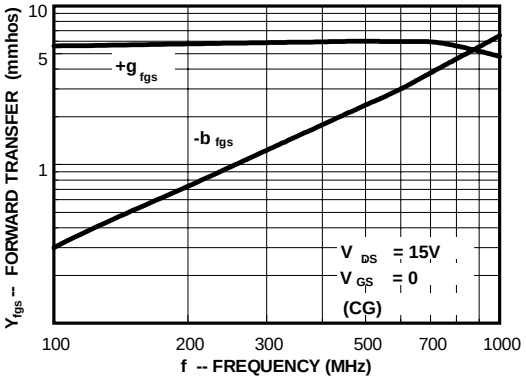
Input Admittance



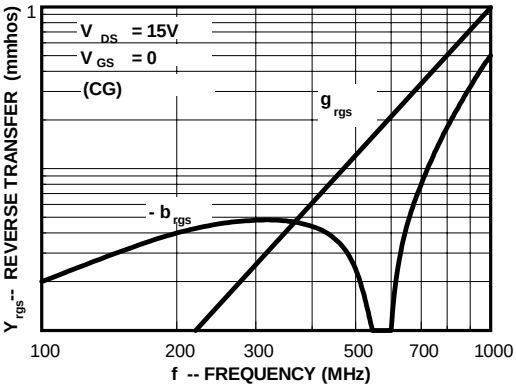
Output Admittance



Forward Transadmittance



Reverse Transadmittance

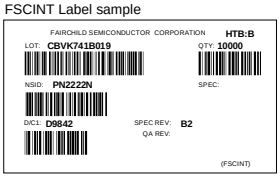


TO-92 Tape and Reel Data

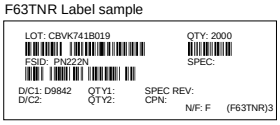
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TO-92 Packaging Configuration: Figure 1.0

FSCINT Label sample

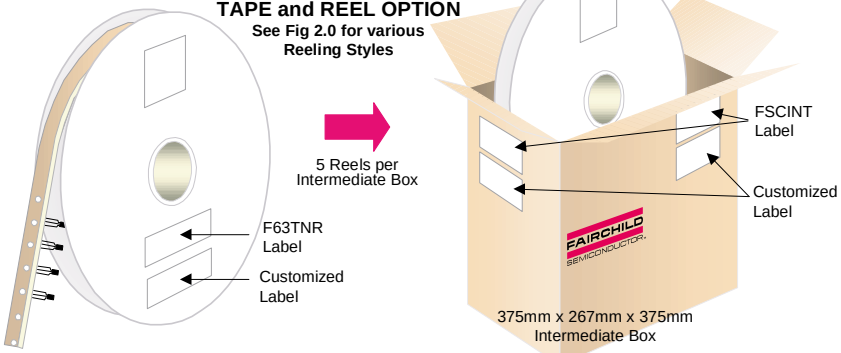


F63TNR Label sample



TAPE and REEL OPTION

See Fig 2.0 for various Reeling Styles



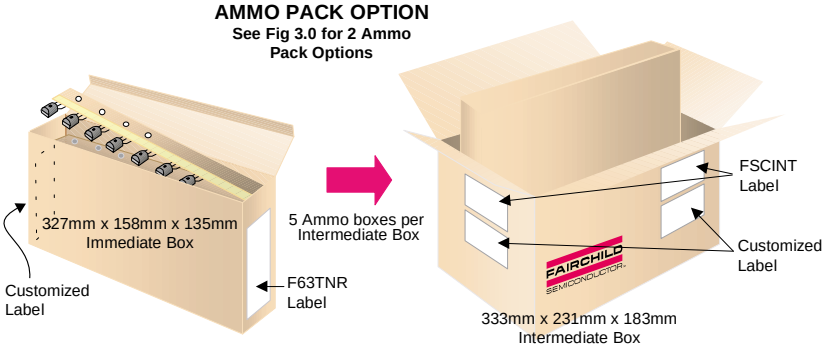
TO-92 TNR/AMMO PACKING INFROMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
Reel weight with components = 1.04 kg
Ammo weight with components = 1.02 kg
Max quantity per intermediate box = 10,000 units

AMMO PACK OPTION

See Fig 3.0 for 2 Ammo Pack Options

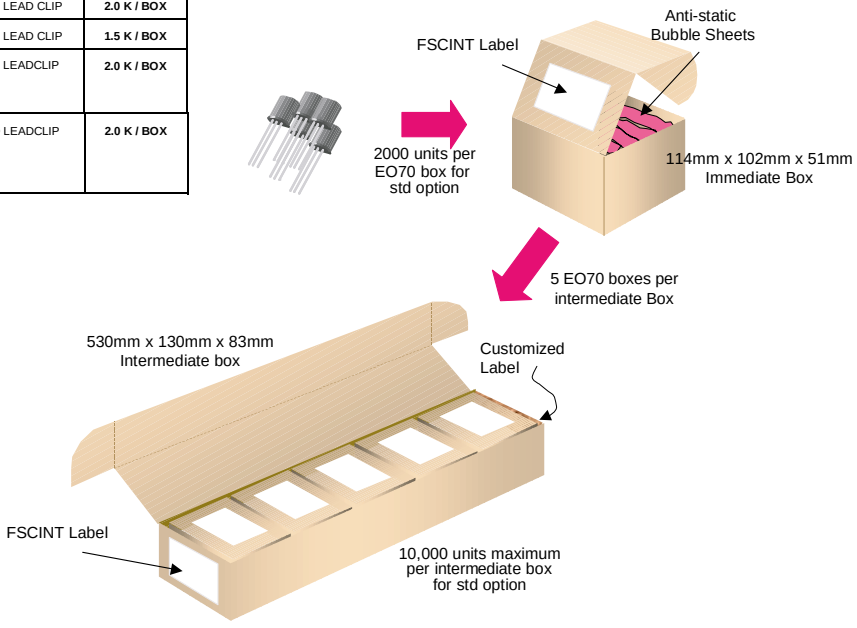


(TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K / BOX
L34Z	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98	NO LEADCLIP	2.0 K / BOX

BULK OPTION

See Bulk Packing Information table

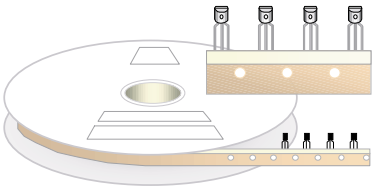


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TO-92 Tape and Reel Data, continued

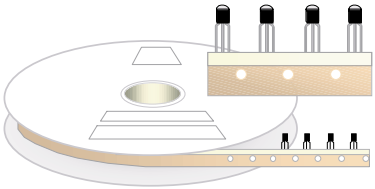
TO-92 Reeling Style
Configuration: Figure 2.0

Machine Option “A” (H)



Style “A”, D26Z, D70Z (s/h)

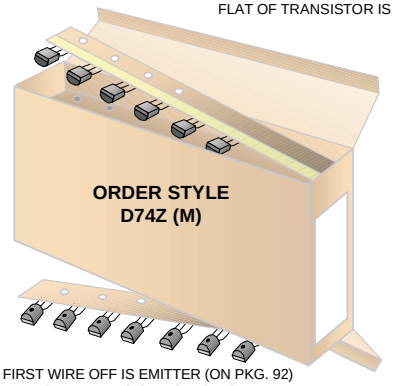
Machine Option “E” (J)



Style “E”, D27Z, D71Z (s/h)

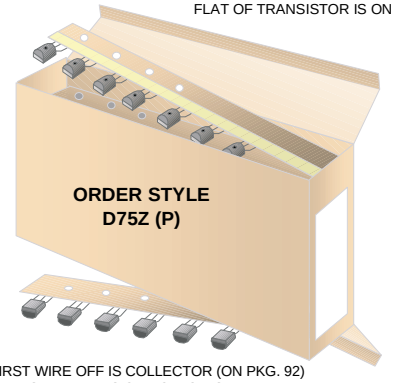
TO-92 Radial Ammo Packaging
Configuration: Figure 3.0

FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

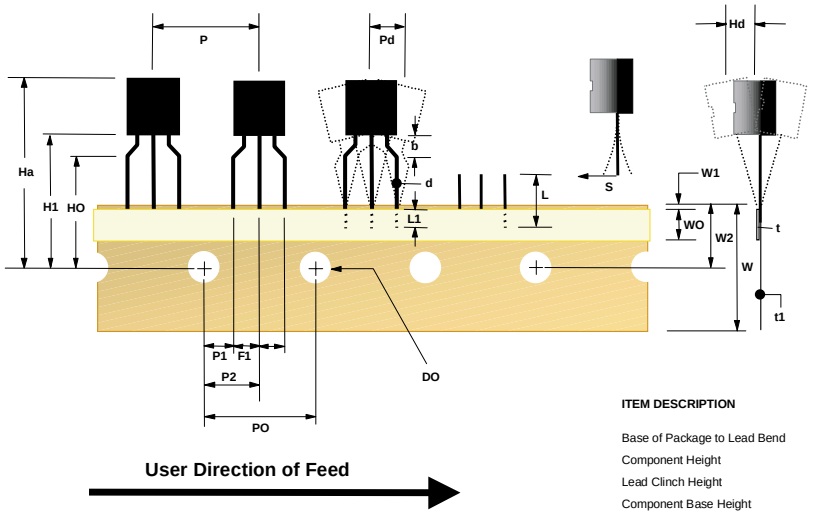
FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

TO-92 Tape and Reel Data, continued

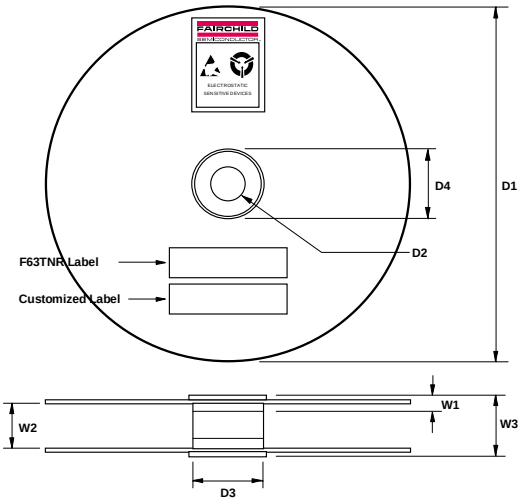
TO-92 Tape and Reel Taping
Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0 .010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

TO-92 Reel
Configuration: Figure 5.0



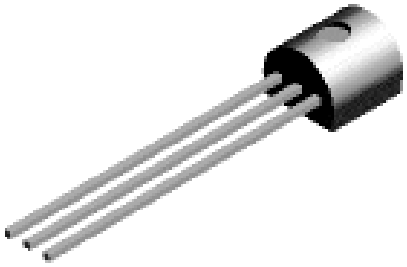
ITEM DESCRIPTION	SYSMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

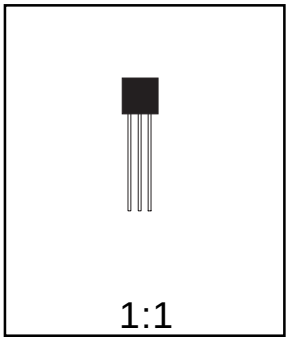
Note: All dimensions are inches

TO-92 Package Dimensions

FAIRCHILD SEMICONDUCTOR™

TO-92 (FS PKG Code 92, 94, 96)





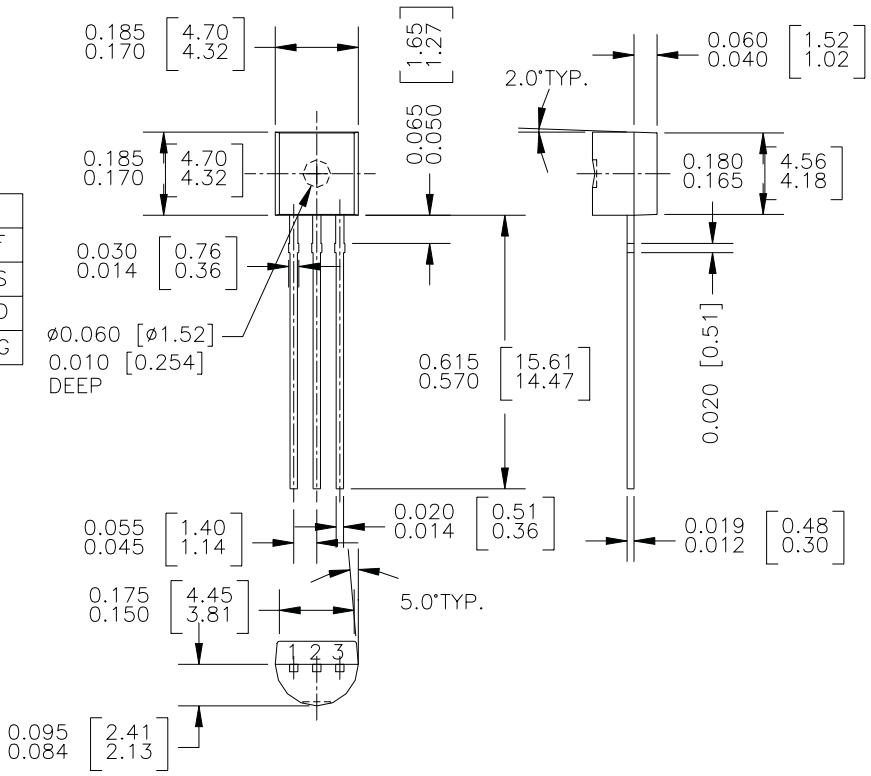
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO−92 (92,94,96)

PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G

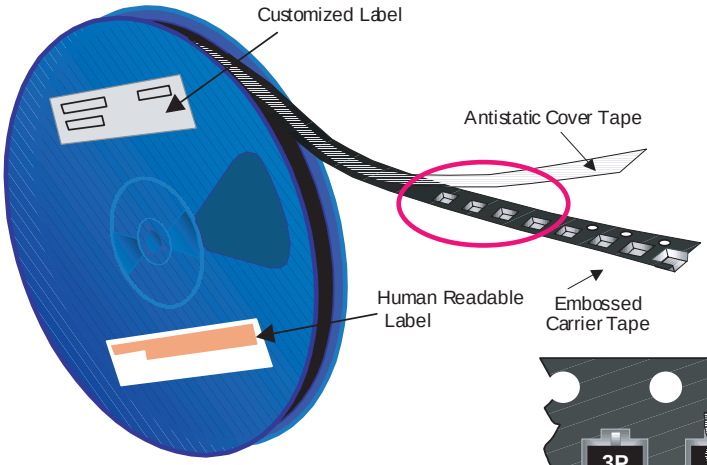


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SOT-23 Tape and Reel Data

FAIRCHILD SEMICONDUCTOR™

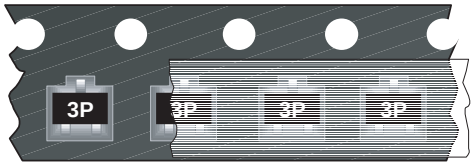
SOT-23 Packaging Configuration: Figure 10



Packaging Description:

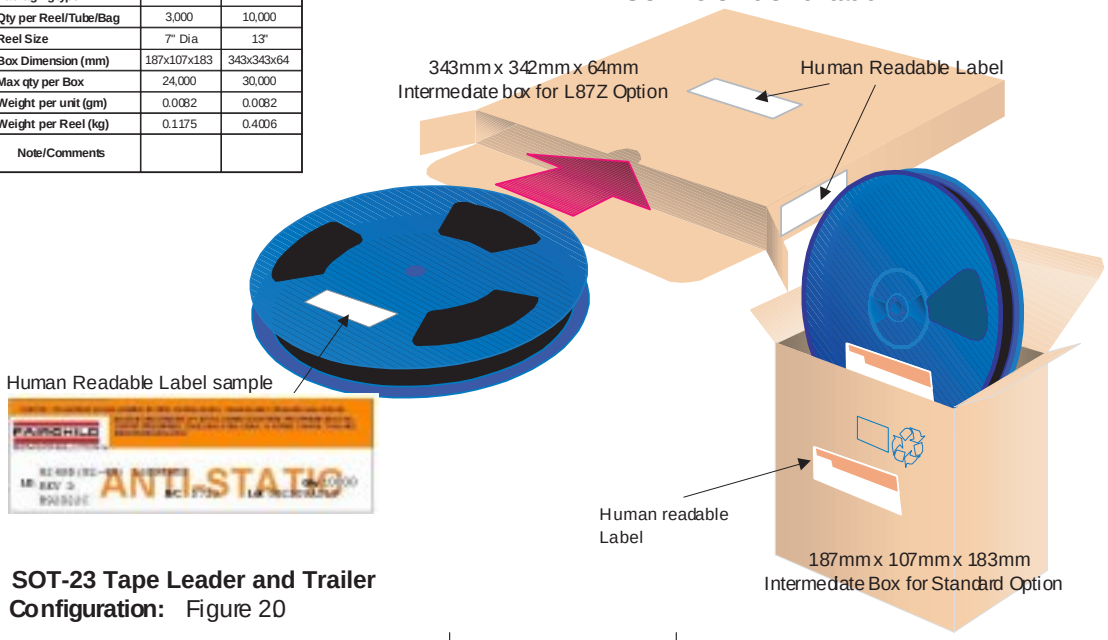
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually labeled and placed inside a standard intermediate made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains eight reels maximum. And these intermediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.

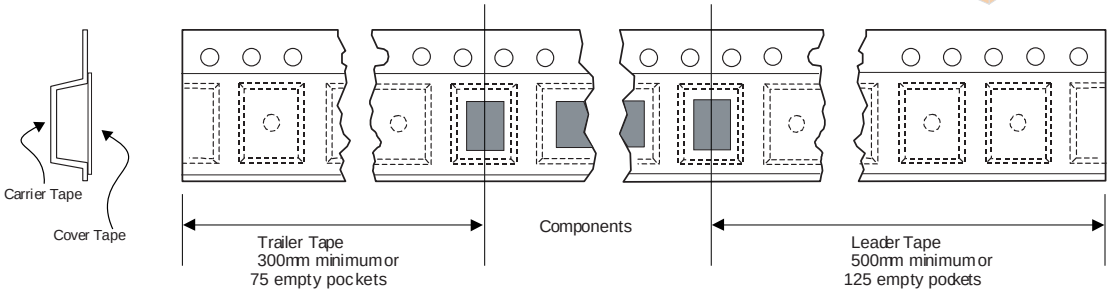


SOT-23 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	187x107x183	343x343x64
Max qty per Box	24,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		

SOT-23 Unit Orientation



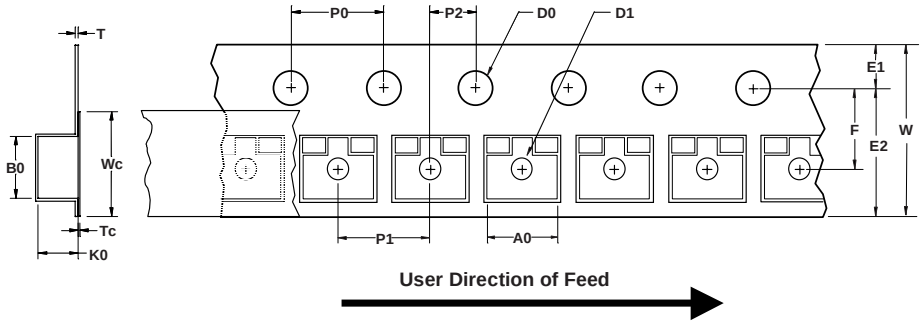
SOT-23 Tape Leader and Trailer Configuration: Figure 20



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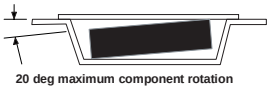
SOT-23 Tape and Reel Data, continued

SOT-23 Embossed Carrier Tape
Configuration: Figure 3.0

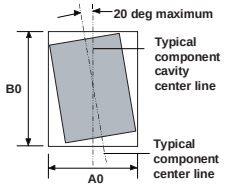


Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

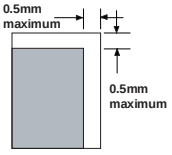
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

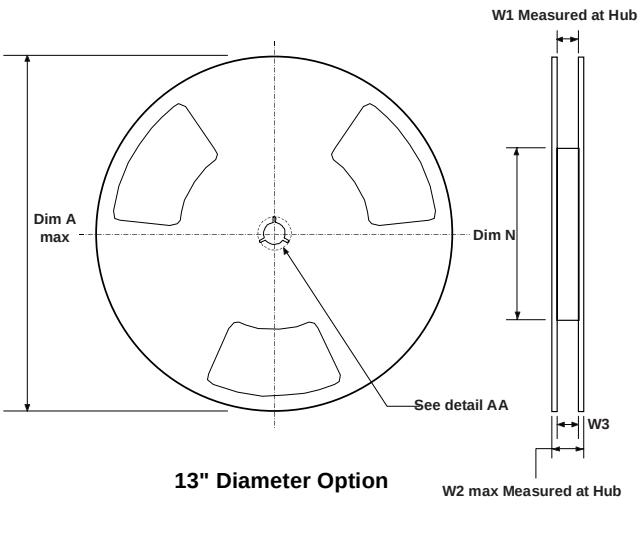


Sketch B (Top View)
Component Rotation

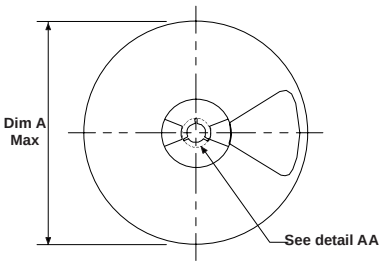


Sketch C (Top View)
Component lateral movement

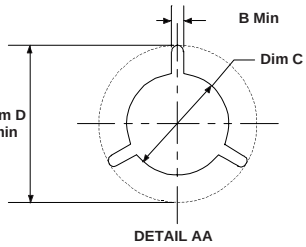
SOT-23 Reel Configuration: Figure 4.0



13" Diameter Option



7" Diameter Option

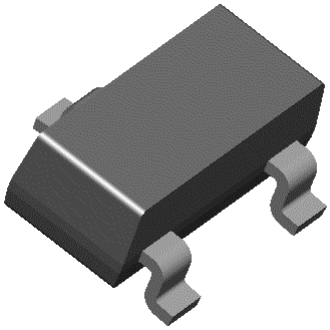


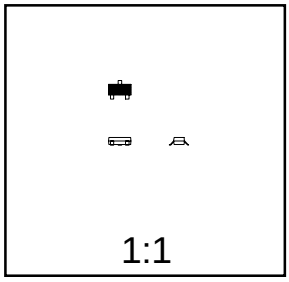
Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9

SOT-23 Package Dimensions

FAIRCHILD SEMICONDUCTOR™

SOT-23 (FS PKG Code 49)

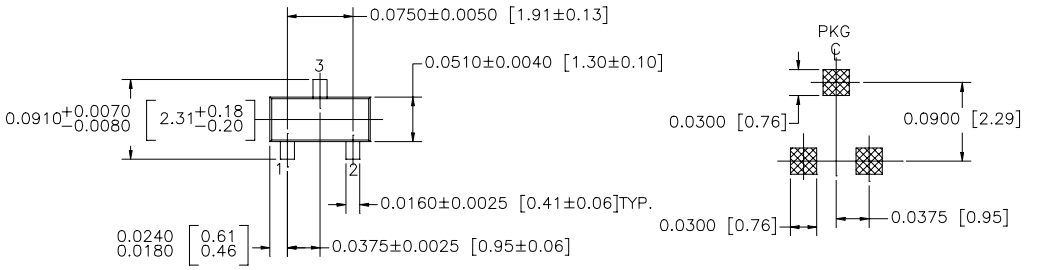


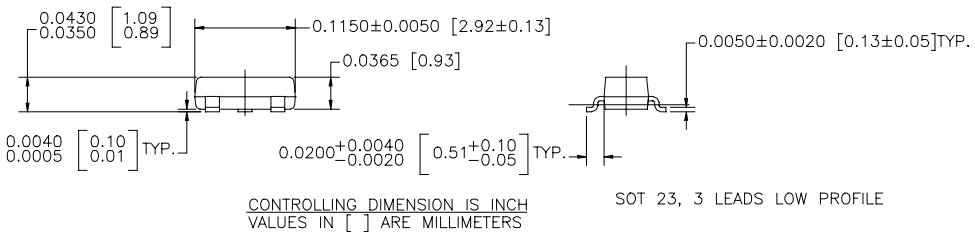


Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0082





NOTE : UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
2. REFERENCE JEDEC REGISTRATION TO−236, VARIATION AB, ISSUE G, DATED JUL 1993

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